



## PARA LIGHT ELECTRONICS CO., LTD.

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# DATA SHEET

# PART NO. : L-C170JRCT

REV : <u>B / 5</u>

CUSTOMER'S APPROVAL :

DRAWING NO. : DS-72-06-0001

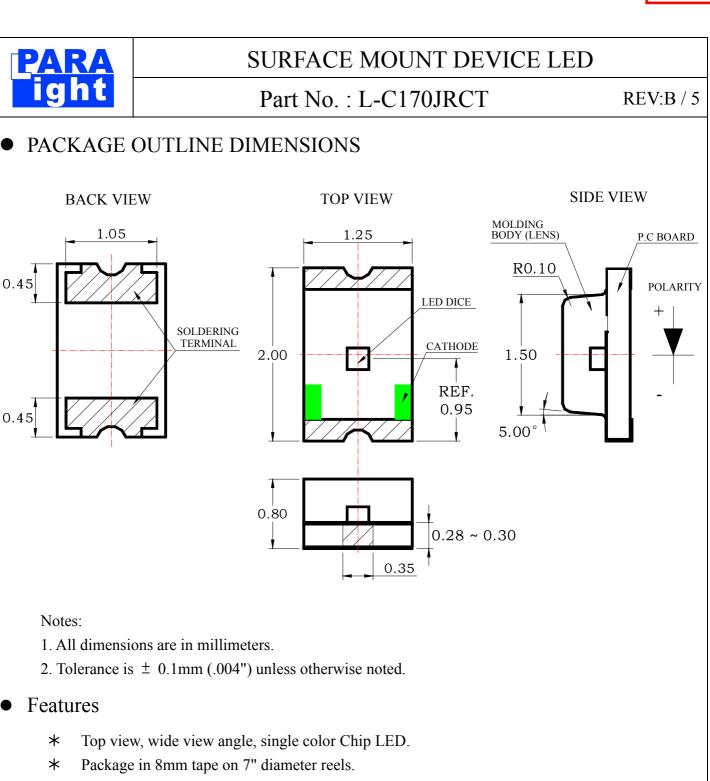
DCC :

PAGE

DATE : 2016-1-29

1 of 14

PARA-FOR-065



- \* Compatible with automatic Pick & Place equipment.
- \* Compatible with Infrared and Wave soldering reflow solder processes.
- \* EIA STD package.
- \* I.C. compatible.
- \* Pb free product.
- \* Meet RoHS Green Product.

#### DRAWING NO. : DS-72-06-0001

#### DATE : 2016-1-29 PAGE 2 of 14

Release by PARALIGHTDCC



### Part No. : L-C170JRCT

#### REV:B / 5

#### • Chip Materials

- \* Dice Material : AlInGaP
- \* Light Color : Super Red
- \* Lens Color : Water Clear

#### • Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Rating	Unit
PD	Power Dissipation	75	mW
IPF	Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	80	mA
IF	Continuous Forward Current	25	mA
-	De-rating Linear From 25°C	0.25	mA/°C
VR	Reverse Voltage	5	V
ESD	Electrostatic Discharge Threshold(HBM)Note A	2000	V
Topr	Operating Temperature Range	$-40 \sim +85$	°C
Tstg	Storage Temperature Range	$-40 \sim +85$	°C

#### Note A :

HBM : Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

### • Electro-Optical Characteristics(Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition	
Luminous Intensity	IV	28	60		mcd	IF=20mA	
Viewing Angle	2 0 1/2		130		deg	Note 2	
Peak Emission	λр		641	nm	Measurement @Peak		
Wavelength	хp		041		11111		
Dominant Wavelength	$\lambda d$		630		nm	IF=20mA	
Spectral Line	Δλ		19		nm		
Half-Width			19				
Forward Voltage	VF		1.9	2.4	V	IF =20mA	
Reverse Current	IR			10	μA	VR = 5V	

DATE : 2016-1-29 PAGE 3 of 14



### Part No. : L-C170JRCT

#### REV:B / 5

#### • Bin Code List

Luminous Intensity(IV), Unit:mcd@20mA						
Bin Code	Min	Max				
Ν	28	45				
Р	45	71				
Q	71	112				

Tolerance of each bin are  $\pm 15\%$ 

#### Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2.  $\theta$  1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength  $\lambda$  d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4. Caution in ESD :

Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

5. Major standard testing equipment by "Instrument System" Model : CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model : 2400.

#### DRAWING NO. : DS-72-06-0001





### Part No. : L-C170JRCT

#### REV:B / 5

#### Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

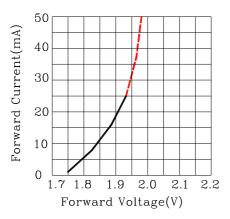


Fig.2 Forward Current vs.Forward Voltage

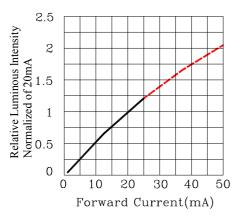
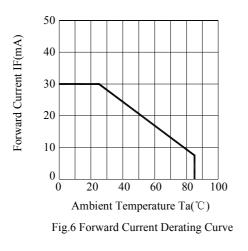


Fig.4 Relative Luminous Intensity vs.Forward Current



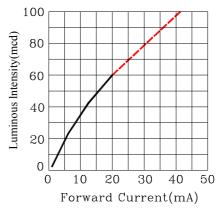


Fig.3 Luminous Intensity vs.Forward Current

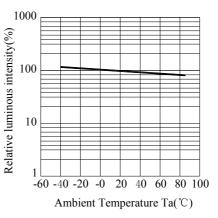
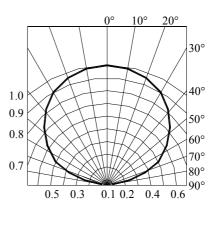


Fig.5 Luminous Intensity vs.Ambient Temperature





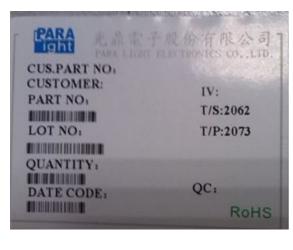
DRAWING NO. : DS-72-06-0001



### Part No. : L-C170JRCT

**REV:B / 5** 

#### • Label Explanation



#### ITEM CODE:PARA LIGHT

PART NO: L-C170JRCT IV --- Luminous Intensity Code LOT NO: ΕM S L в А C A---EM: Emos Code B---S:SMD

L---Local

D---Year

E---Month

F---SPEC.

PACKING QUANTITY OF BAG :

3000pcs for 150, 170, 110, 155, 115 series

12

D

09

Е

0110

F

4000pcs for 191 series

5000pcs for 192 series

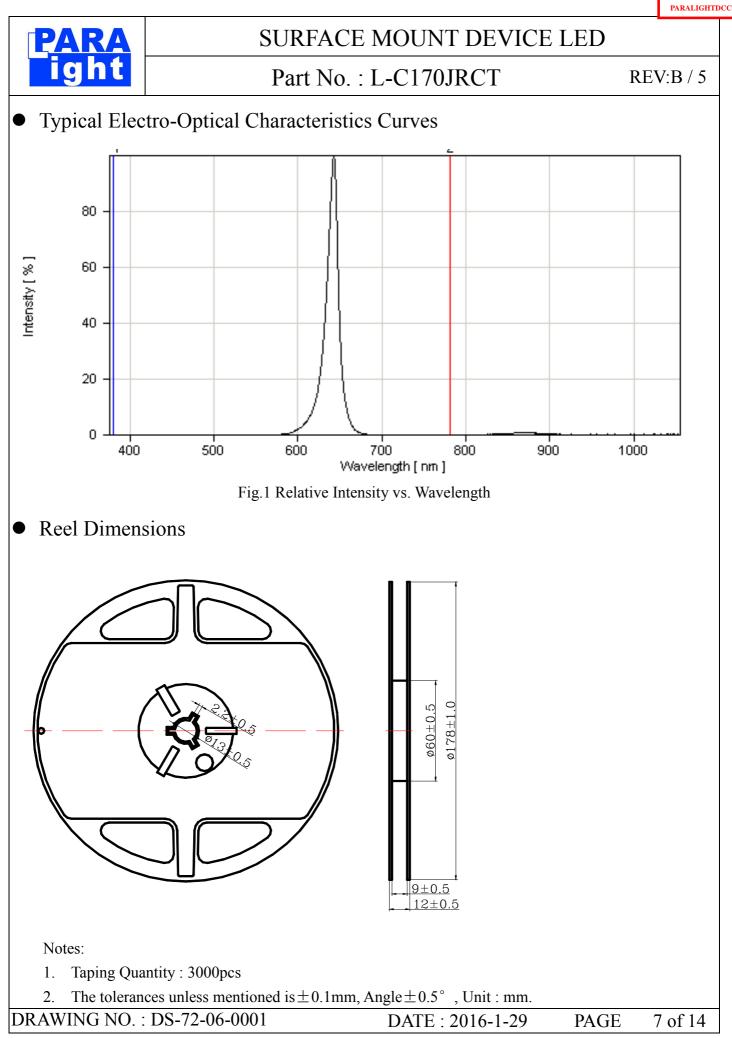
DATE CODE: <u>2012</u> <u>09</u> <u>10</u> G Η I

G---- Year H--- Month I --- Day

DRAWING NO. : DS-72-06-0001

DATE : 2016-1-29 PAGE 6 of 14

PARA-FOR-068

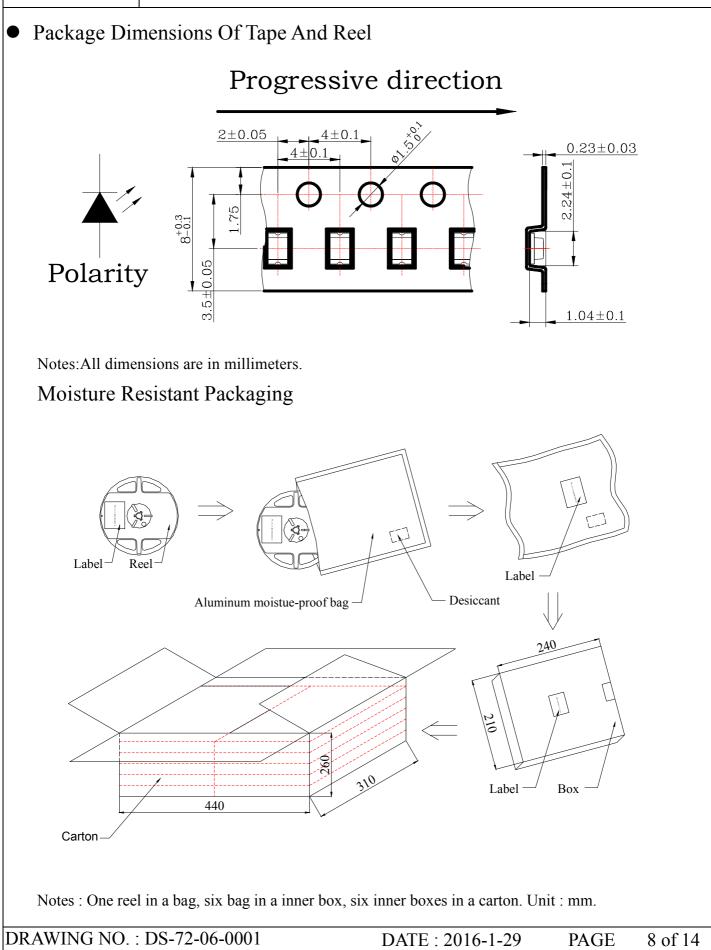


Release by



### Part No. : L-C170JRCT

REV:B / 5





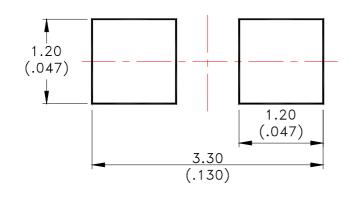
### Part No. : L-C170JRCT

REV:B / 5

### • Cleaning

- \* If cleaning is required , use the following solutions for less than 1 minute and less than  $40^{\circ}$ C.
- \* Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

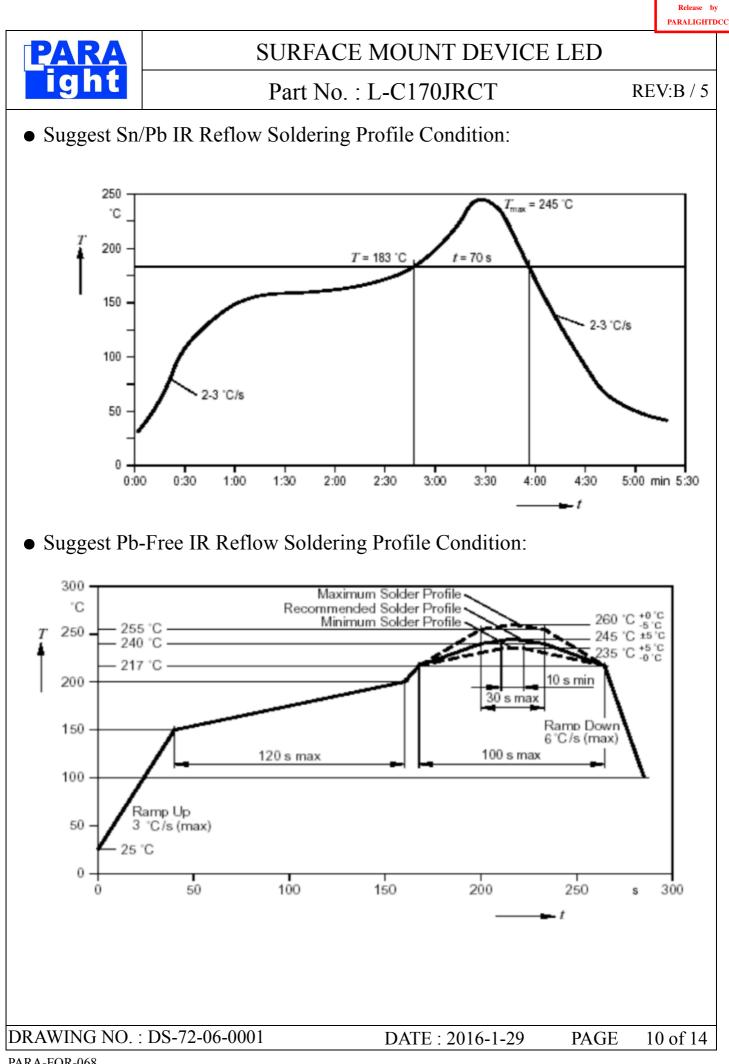
### Suggest Soldering Pad Dimensions



Direction of PWB camber and go to reflow furnace

DRAWING NO. : DS-72-06-0001

DATE : 2016-1-29 PAGE 9 of 14



PARA-FOR-068



### Part No. : L-C170JRCT

REV:B / 5

### • CAUTIONS

#### 1. Application Limitation :

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application).Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

#### 2.Storage :

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at  $30^{\circ}$ C or less and 90%RH or less.

After opening the package: The LED's floor life is 1 year under  $30^{\circ}$ C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours

#### 3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature. Recommended soldering condition.

Reflow Soldering :

Pre-heat 120~150°C, 120sec. MAX., Peak temperature : 240°C Max. Soldering time : 10 sec Max. Soldering Iron : (Not recommended)

Temperature 300°C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron :

20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering. Wave soldering :

Pre-heat 100°C Max, Pre-heat time 60 sec. Max, Solder wave 260°C Max, Soldering time 5 sec. Max. preformed consecutively cooling process is required between 1<sup>st</sup> and 2<sup>nd</sup> soldering processes.

DRAWING NO. : DS-72-06-0001

DATE : 2016-1-29 PAGE 11 of 14



### Part No. : L-C170JRCT

### REV:B / 5

Part P	NO. : $L-C1/0JRC1$	KI	2V:B/
ng			
dering :			
mp:150-180°C,120sec.Max.			
emp:Temperature Of Solderi	ng Pot Over 230°C,40sec.Max.		
rature:260°C , 5sec.			
etition:2 Times Max.			
der Paste Formula 93.3 Sn/3	.1 Ag/3.1 Bi /0.5 Cu		
on (Not Recommended) :			
np:350°C Max.			
on:30w Max.			
ime:3 Sec. Max. One Time.			
ng :			
mp:150°C Max. 120 Sec. M	lax.		
265°C Max.			
Sec. Max.			
cuit model A	Circuit model B		
		-	
	D's could be found due to the Vf If	faharastaristics	of LED
ee of originaless between LE	D S could be found due to the VI-II		OI LED
	ng dering : mp:150-180°C,120sec.Max. emp:Temperature Of Solderi rature:260°C , 5sec. etition:2 Times Max. der Paste Formula 93.3 Sn/3 ron (Not Recommended) : np:350°C Max. on:30w Max. ime:3 Sec. Max. One Time. ng : mp:150°C Max. 120 Sec. M 265°C Max. Sec. Max. suit model A	ng dering : mp:150-180°C,120sec.Max. emp:Temperature Of Soldering Pot Over 230°C,40sec.Max. rature:260°C , 5sec. etition:2 Times Max. der Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu ron (Not Recommended) : np:350°C Max. on:30w Max. ime:3 Sec. Max. One Time. ng : mp:150°C Max. 120 Sec. Max. 265°C Max. Sec. Max. suit model A Circuit model B A Circuit model B	ng dering : mp:150-180°C,120sec.Max. emp:Temperature Of Soldering Pot Over 230°C,40sec.Max. rature:260°C · 5sec. etition:2 Times Max. der Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu on (Not Recommended) : np:350°C Max. on:30w Max. ime:3 Sec. Max. One Time. ng : mp:150°C Max. 120 Sec. Max. 265°C Max. Sec. Max. sec. Max. tuit model A Circuit model B



#### Part No. : L-C170JRCT

REV:B / 5

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#### 6.Reliability Test Classification Test Item **Test Condition Reference Standard** Ta= Under Room Temperature As Per Data MIL-STD-750D:1026 (1995) Sheet Maximum Rating **Operation** Life MIL-STD-883D:1005 (1991) \*Test Time= 1000HRS JIS C 7021:B-1 (1982) (-24HRS,+72HRS)\*@20mA. **High** Temperature **IR-Reflow In-Board**, 2 Times MIL-STD-202F:103B(1980) Endurance Test High Humidity $Ta = 65 \pm 5^{\circ}C$ , RH= 90~95% JIS C 7021:B-11(1982) Storage \*Test Time= 1000HRS±2HRS High Temperature $Ta = 105 \pm 5^{\circ}C$ MIL-STD-883D:1008 (1991) Storage Test Time= 1000HRS (-24HRS,72HRS) JIS C 7021:B-10 (1982) Low Temperature Ta= -55±5℃ JIS C 7021:B-12 (1982) Storage \*Test Time=1000HRS (-24HRS,72H RS) MIL-STD-202F:107D (1980) Temperature 105±5℃ -55±5℃ MIL-STD-750D:1051(1995) Cycling 10mins 10mins 100 Cycles MIL-STD-883D:1010 (1991) JIS C 7021:A-4(1982) MIL-STD-202F:107D(1980) IR-Reflow In-Board, 2 Times Thermal 105±5℃ -55℃±5℃ MIL-STD-750D:1051(1995) Shock 10mins 10mins 100 Cycles MIL-STD-883D:1011 (1991) Environmental MIL-STD-202F:210A(1980) Test Solder Tsol= $260 \pm 5^{\circ}$ C MIL-STD-750D:2031(1995) Resistance Dwell Time= $10 \pm 1$ sec JIS C 7021:A-1(1982) MIL-STD-202F:208D(1980) Tsol= $235 \pm 5^{\circ}$ C MIL-STD-750D:2026(1995) Immersion time $2\pm 0.5$ sec Solder ability MIL-STD-883D:2003(1991) Immersion rate $25\pm2.5$ mm/sec IEC 68 Part 2-20 Coverage $\geq 95\%$ of the dipped surface JIS C 7021:A-2(1982)

7.Others:

The appearance and specifications of the product may be modified for improvement without notice.

DRAWING NO. : DS-72-06-0001

DATE : 2016-1-29 PAGE 13 of 14

